

**AMD Socket F  
Retention Module & Back Plate**

P/N : CL-O0010

Application for AMD socket F Motherboard.



*Recommend for Server Use*



Back View

**Specification**

Back Plate	
Dimension	114 (L)x 66 (W)
Thickness	2mm
Material	SPCC / Nickel Plated
Insulator	
Dimension	114.6 (L)x 66.6 (W)
Thickness	0.22mm
Material	PET Film & Fish Paper Composite
Weight	100g

**Dimension**

